

SLVS372B - JUNE 2001 - REVISED JANUARY 2002

170-μVrms ZERO-RIPPLE SWITCHED CAP BUCK-BOOST CONVERTER FOR VCO SUPPLY

FEATURES

- Wide Input Voltage Range:
 - 1.8 V To 5.5 V for 2.7-V, 3-V, 3.3-V Output (TPS60240/2/3)
 - 2.7 V To 5.5 V for 5-V Output (TPS60241)
- 170-μVrms Zero Ripple Output:
 - at 20 Hz to 10 MHz Bandwidth
- Minimum Number of External Components
 - No Inductors
 - Only Small Ceramic Chip Capacitors
- Up to 90% Efficiency
- Regulated 3.3-V (TPS60240), 5-V (TPS60241),
 3-V (TPS60243), and 2.7-V (TPS60242) Output
 Voltage With ±2.5% Accuracy Over Load
- Up to 25-mA Output Current
- Shutdown Mode: 0.1 μA Typical
- Thermal Protection and Current Limit
- Microsmall 8-Pin MSOP Package
- EVM Available TPS60241EVM-194

APPLICATIONS

- VCO and PLL Power for:
 - PDA Phones
 - Cellular Phones
 - PCMCIA Modems
- Smartcard Readers

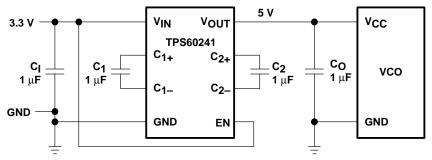
- Digital Cameras
- MP3 Players
- SIM Modules
- Electronic Games
- Memory Backup
- Handheld Meters
- Bias Supplies

DESCRIPTION

The TPS6024x is a switched capacitor voltage converter, ideally suited for VCO and PLL applications that require low noise and tight tolerances. Its dual-cap design uses four ceramic capacitors to provide ultralow output ripple yet high efficiency, while eliminating the need for inefficient linear regulators.

A wide input supply voltage range of 2.7 V to 5.5 V makes the TPS6024x ideal for lithium-based battery applications. The TPS60240/2/3 operates down to 1.8 V, supporting a 3.3-V, 2.7-V, 3-V output from two-cell, nickel- or alkaline-based chemistries. The devices work equally well for low EMI dc/dc step-up conversion without the need for an inductor. The high switching frequency (typical 160 kHz) promotes the use of small surface-mount capacitors, saving board space. The converter's shutdown mode conserves battery energy.

typical application circuit





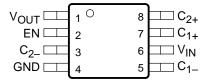
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



description(continued)

The devices are thermally protected and current-limited for reliable operation even under persisting fault conditions. Normal quiescent current (ground pin current) is only $250 \,\mu\text{A}$, and typically $0.1 \,\mu\text{A}$ in shutdown mode. The TPS6024x devices come in a thin, 8-pin MSOP (DGK) package with a component height of only 1,1 mm.

DGK PACKAGE (TOP VIEW)



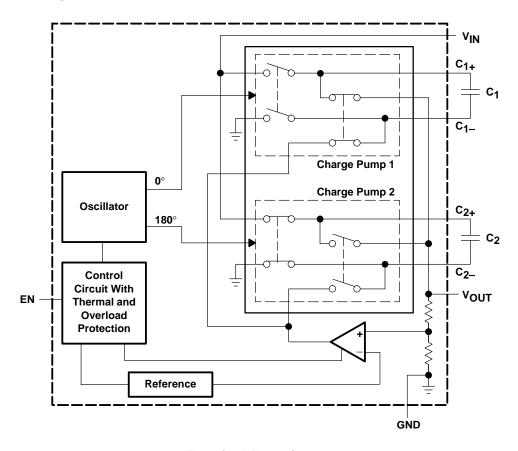
AVAILABLE OPTIONS

TA	PART NUMBERT	PACKAGE MARKING	PACKAGE	OUTPUT VOLTAGE (V)
-40°C to 85°C	-40°C to 85°C TPS60241DGKR AUB DGK (8-pin MSOP)		5 V	
	TPS60240DGKR	ATM	DGK (8-pin MSOP)	3.3 V
-40°C to 85°C	TPS60242DGKR	AYF	DGK (8-pin MSOP)	2.7 V
	TPS60243DGKR	AYG	DGK (8-pin MSOP)	3 V

[†] This package type is available taped and reeled only. Quantity is 2500 units per reel (e.g., TPS60241DGKR). The devices are also available on mini reel with 250 units per reel. To order this packaging option, replace the R with a T in the part number (e.g., TPS60261DGKT).



functional block diagram



Terminal Functions

TERMI	TERMINAL		
NAME	NO.	1/0	DESCRIPTION
C ₁₊	7		Positive terminal of the flying capacitor C ₁
C ₁₋	5		Negative terminal of the flying capacitor C ₁
C ₂₊	8		Positive terminal of the flying capacitor C ₂
C ₂ -	3		Negative terminal of the flying capacitor C ₂
EN	2	1	Enable terminal, active high
GND	4		Ground
VIN	6	I	Supply voltage input TPS60241: 2.7 V to 5.5 V, TPS60240/2/3: 1.8 V to 5.5 V. Bypass $V_{\mbox{IN}}$ to GND with a 1- μ F external capacitor (C _I).
VOUT	1	0	Regulated power output. Bypass V_{OUT} to GND with a 1- μ F external filter capacitor (C _O). TPS60241: regulated 5-V output, TPS60240: regulated 3.3-V output, TPS60242: regulated 2.7-V output, TPS60243: regulated 3-V output

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detailed description

operating principle

The TPS6024x charge pump is a fixed-frequency, dual-phase charge pump that provides 25 mA of continuous supply current for low-noise applications such as VCOs used in cell phones and wireless appliances.

Low-noise operation results from using a proprietary dual-phase charge pump topology that relies on an operational amplifier in the feedback loop to reduce ripple. During the first phase, C_1 is charged to the supply voltage. Terminal C_{1+} is connected to V_{IN} , and C_{1-} is connected to GND. In the second phase, C_{1-} is connected to the output of the operational amplifier, and C_{1+} is connected to V_{OUT} . The operational amplifier then adjusts its output until the output V_{OUT} delivers the correct voltage to make the resistor divided feedback point equal to the reference voltage. During this second phase, C_2 is charged to supply voltage. Terminal C_{2-} is connected to GND, and C_{2+} is connected to V_{IN} . Phase one is then repeated with C_2 , now acting to provide charge to the output in place of C_1 , which is connected to the supply. The dual-phase operation lowers the output ripple voltage significantly compared to a standard single-phase charge pump. In addition, the linear feedback of the operational amplifier eliminates the ripple during discharge of the output capacitor (C_0).

shutdown

Driving EN low disables the converter. This disables the internal circuits and reduces input current to typically 0.1 μ A. In this mode, the load is disconnected from the supply voltage. The device exits shutdown once EN is set to a high level.

start-up procedure

The converter is enabled when EN is set from logic low to high. The start-up time to reach 90% of the nominal output voltage is typically 0.5 ms at load currents lower than 10 mA and with an output capacitor of 1 μ F. Increasing the values of C_O delays the start-up time.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{DD}	0.3 V to 6 V
Power dissipation, P _D	Internally limited
Voltage EN	0.3 V to 6 V
Voltage C ₂ -, C ₁	-0.3 V to V _I or 5.5 V, whichever is lowest
Voltage C_{2+} , C_{1+}	-0.3 V to V _I , V _O or 5.5 V, whichever is lowest
Junction temperature, T _J	125°C
Storage temperature, T _{stq}	
Shortcircuit output current	80 mA maximum

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DGK	376 mW	3.76 mW/°C	207 mW	150 mW

NOTE: The thermal resistance junction to ambient of the DGK package is $R_{TH-JA} = 150$ °C/W.



recommended operating conditions

			MIN	NOM	MAX	UNIT	
M.	lanut valta sa sana	TPS60240, TPS60242, TPS60243	1.8		5.5	.,	
VI	Input voltage range	TPS60241	2.7		5.5	V	
IO	Output current range	All devices		25		mA	
Cl	Input capacitor			1		μF	
C_1, C_2	Flying capacitors			1		μF	
CO	Output capacitor			1		μF	
TA	Operating temperature range		-40		85	°C	

electrical characteristics for TPS6024X at T_A = 25°C, C_I = C_O =1 μ F, C_1 = C_2 = 1 μ F (unless otherwise noted), limits apply over the specified temperature range, –40°C to 85°C

	PAI	RAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
		TPS60240 Assu	red start-up	$I_O \le 5$ mA, $R_L = 600 \Omega$	1.8		5.5	
V _I Input voltage		TPS60241 Assu	red start-up	$I_O \le 12 \text{ mA}, R_L = 417 \Omega$	2.7		5.5	l ,,
VI	V _I Input voltage	TPS60242 Assu	red start-up	$I_O \le 12 \text{ mA}, R_L = 225 \Omega$	1.8		5.5	V
		TPS60243 Assu	red start-up	$I_O \le 10 \text{ mA}, R_L = 300 \Omega$	1.8		5.5	
				$1.8 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 5 \text{ mA}$				
		TPS60240		$2.4 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 25 \text{ mA}$	3.2175	3.3	3.3825	
		TD000044		$2.7 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 12 \text{ mA}$	4.075	_	5 405	
.,	0	TPS60241		$3 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 25 \text{ mA}$	4.875	5	5.125	
۷O	Output voltage	TD000040		$1.8 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 12 \text{ mA}$	0.0005		0.7075	V
		TPS60242		$2.3 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 25 \text{ mA}$	2.6325	2.7	2.7675	
		TD000040		$1.8 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 10 \text{ mA}$	0.005	_	0.075	
		TPS60243		$2.3 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{O}} \le 25 \text{ mA}$	2.925	3	3.075	
		TD0000 40/0/0	Nominal	2 V ≤ V _I ≤ 5.5 V	12			
		TPS60240/2/3	Short circuit	V _I = 2 V			80	
Ю	Output current	TDCC0044	Nominal	2.7 V ≤ V _I ≤ 5.5 V	12			mA
		TPS60241		V _I = 3.25 V			80	
fosc		Internal clock so	ource		100	160	220	kHz
۷ _n	Output noise	TPS60240/2/3 TPS60241		V_I < 2.5 V, I_O = 5 mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, C_O = 4.7 μF		170		i
**	voltage			V_I = 2.7 V, I_O = 5 mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, C_O = 4.7 μF				μV RMS
V _{I(H)}	EN	Logic high input	voltage VOH		1.3		5.5	V
$V_{I(L)}$	EN	Logic low input	voltage V _{OL}		-0.2		0.4	V
I _{I(H)}	EN	Logic high input	current				100	nA
I _{I(L)}	EN	Logic low input	current				100	nA
t(EN)	EN	Start-up time		$V_O > 90\%$ of $V(NOM)$ 0.1 mA $\leq I_O \leq$ 10 mA, $C_O = 1 \mu F$	0.5			ms
		TPS60240		I _O = 5 mA, V _I = 1.8 V		89.6%		
		TPS60241		I _O = 10 mA, V _I = 2.7 V		90.8%		
η	Efficiency	TPS60242		I _O = 10 mA, V _I = 1.8 V	73%			
		TPS60243		I _O = 10 mA, V _I = 1.8 V		81%		

electrical characteristics for TPS6024X at T_A = 25°C, C_I = C_O =1 μ F, C_1 = C_2 = 1 μ F (unless otherwise noted), limits apply over the specified temperature range, –40°C to 85°C (continued)

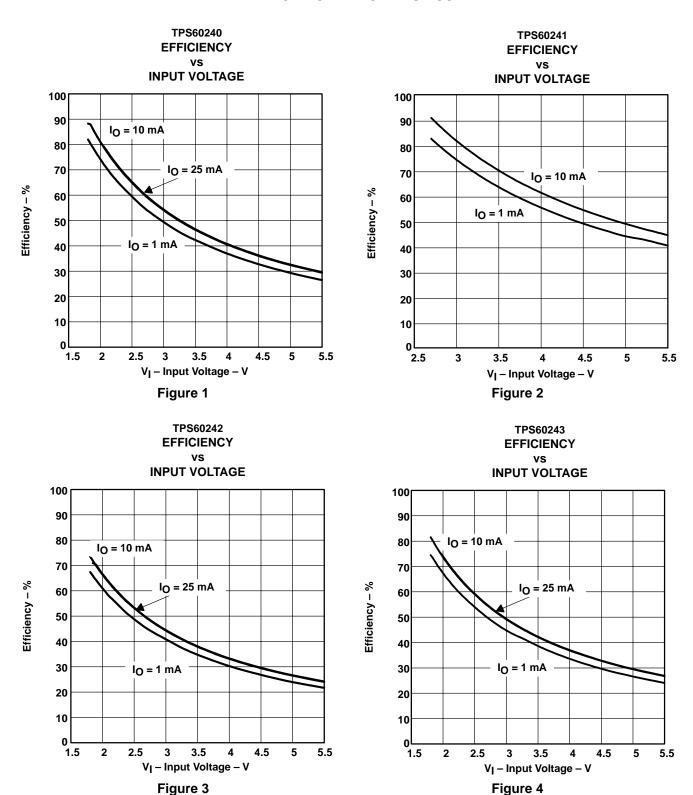
PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Quiescent		$I_{O} = 0 \text{ mA}, V_{I} = 3 \text{ V}$		250	325	
IQ (current		In shutdown mode		0.1	1	μΑ
	Thermal	Temperature activated			160		0.0
	shutdown	Temperature deactivated			140		°C

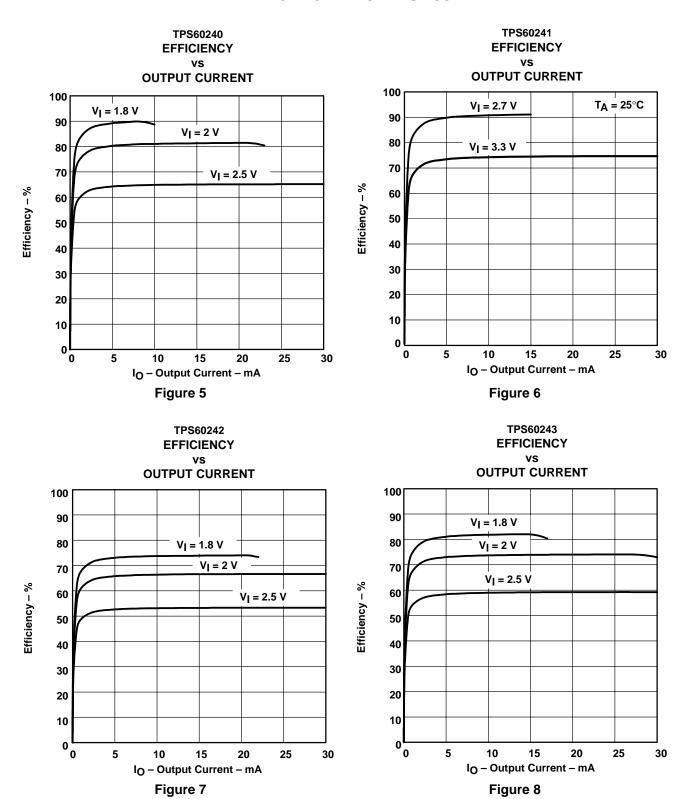
TYPICAL CHARACTERISTICS

Table of Graphs

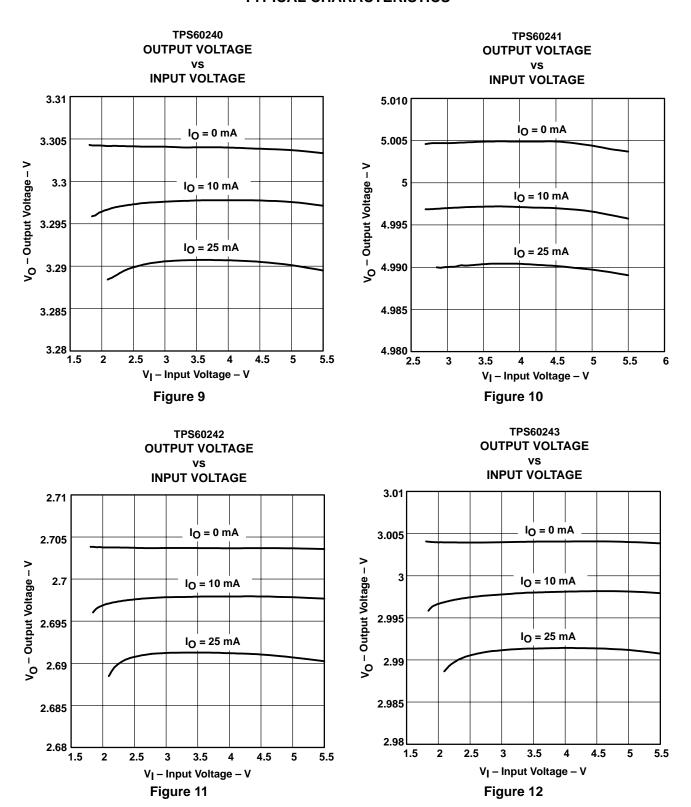
			FIGURE
		vs Input voltage	1–4
	Efficiency	vs Output current	5–8
		vs Input voltage	9–12
۷o	Output voltage	vs Output current	13–16
		vs Free-air temperature	17
	•	vs Input voltage	18
	Quiescent current	vs Free-air temperature	19
I _{L(sd)}	Shutdown current	vs Free-air temperature	20
٧n	Output noise voltage	vs Output current	21
	Maximum output current	vs Input voltage	22–25
	Load transient response		26
	Start-up timing		27
	Line transient response		28
	Noise voltage spectrum		29
	Output voltage ripple	vs Time	30



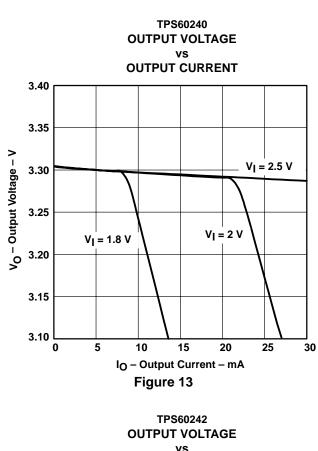


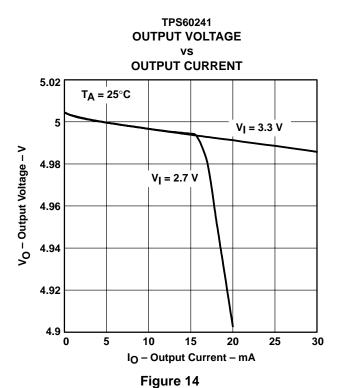












2.80
2.75

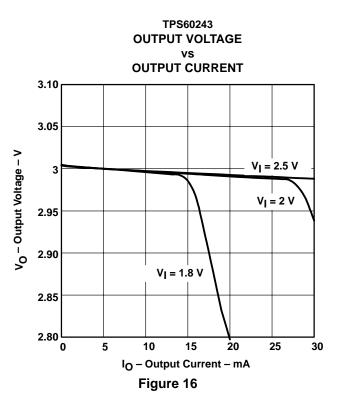
2.75

2.70

V_I = 2.5 V

V_I = 2.5 V

V_I = 1.8 V



30

2.55

2.50

0

5

10

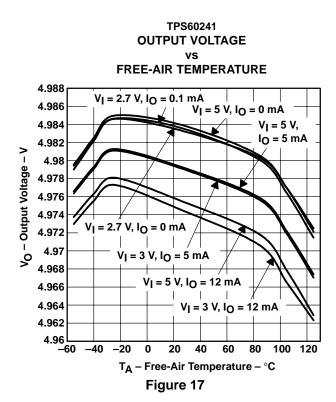
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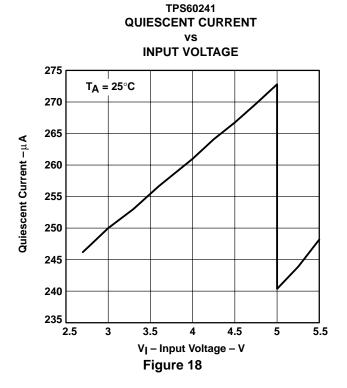
IO - Output Current - mA

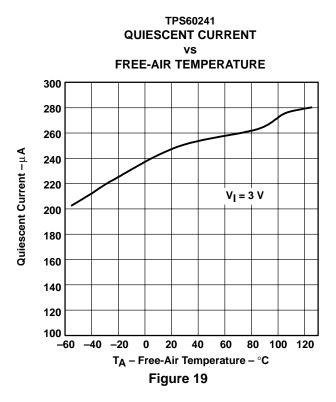
Figure 15

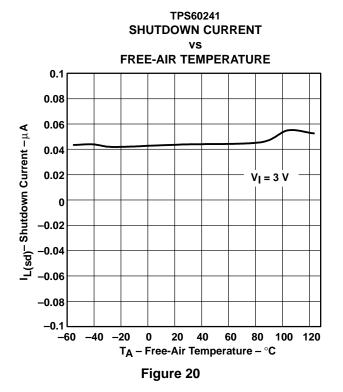
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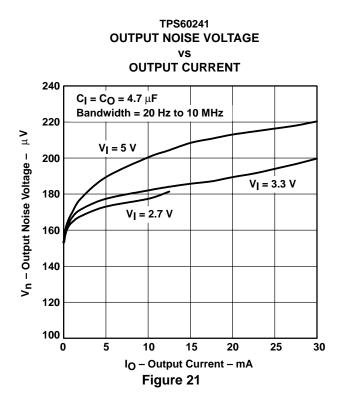
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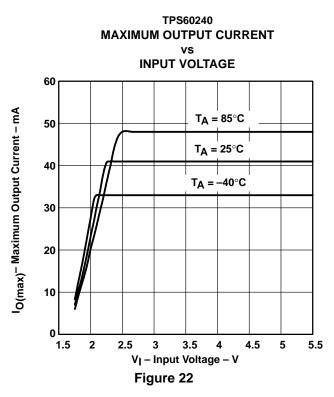


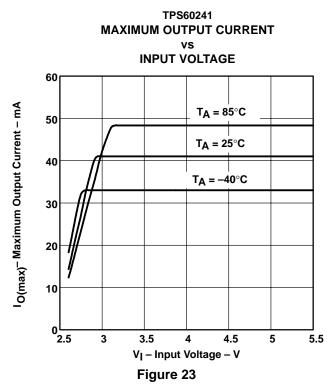


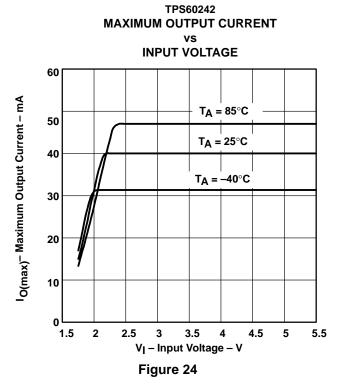




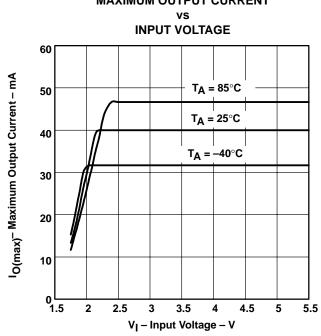








TPS60243 MAXIMUM OUTPUT CURRENT



LOAD TRANSIENT RESPONSE

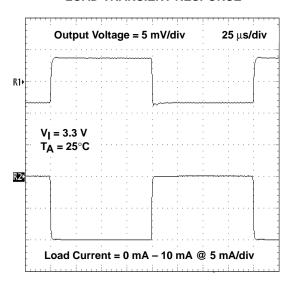


Figure 26

START-UP TIMING

Figure 25

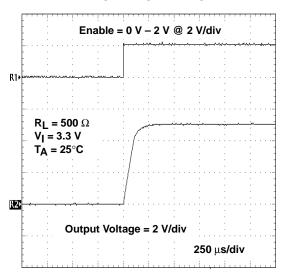


Figure 27

LINE TRANSIENT RESPONSE

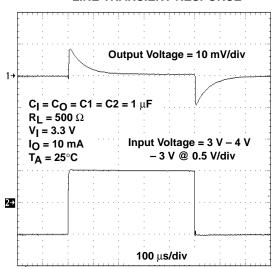
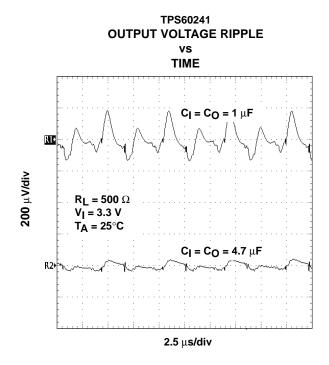


Figure 28

TPS60241 **NOISE VOLTAGE SPECTRUM** $10~\mu V rms$ √Hz $C_I = C_O = 4.7 \mu F$ $C1 = C2 = 1 \mu F$ $R_0 = 500 \Omega$ $V_{I} = 3.3 \text{ V}$ T_A = 25°C 100 nVrms √Hz 10 Hz 100 Hz 1 kHz 10 kHz 100 kHz

Figure 29



NOTE: Scope triggered by voltage at flying capacitors, noise removed by averaging function and bandwidth limit 20 MHz.

Figure 30



APPLICATION INFORMATION

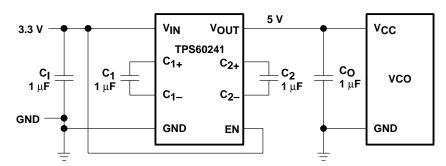


Figure 31. 5-V Low-Noise VCO Supply From 3.3-V Input

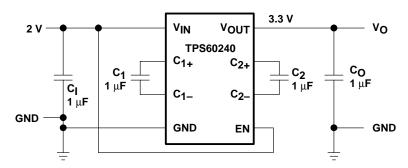


Figure 32. 2-V to 3.3-V Low-Noise Converter

output voltage ripple

The output voltage ripple depends on the capacitors used. Table 1 illustrates the dependence between output voltage ripple and capacitor selection.

Table 1. Output Voltage Ripple and Capacitor Selection

Cl	co	c ₁	C ₂	OUTPUT VOLTAGE RIPPLE [μVrms]
1 μF	1 μF	1 μF	1 μF	288
2.2 μF	2.2 μF	1 μF	1 μF	212
4.7 μF	4.7 μF	1 μF	1 μF	183
4.7 μF	1 μF	1 μF	1 μF	272
1 μF	4.7 μF	1 μF	1 μF	185

NOTE: $V_1 = 3.3 \text{ V}$, $V_0 = 5 \text{ V}$, $R_L = 500 \Omega$, $T_A = 25^{\circ}C$



APPLICATION INFORMATION

components

For the best output ripple performance, low-ESR ceramic capacitors are recommended (see Table 2).

Table 2. Recommended Capacitors

PART	MANUFACTURER	PART NUMBER	VALUE	TOLERANCE	DIELECTRIC MATERIAL	PACKAGE	RATED VOLTAGE
	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
Cl	TDK	C2012X5R0J475K	4.7 μF	10%	X5R	0805	6.3
_	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
CO	TDK	C2012X5R0J475K	4.7 μF	10%	X5R	0805	6.3
C ₁ , C ₂	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
C _F	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10

layout consideration

In order to get optimal noise behavior, keep the power lines to the capacitors and load as short as possible. Use of power planes is recommended.

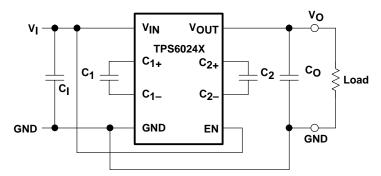


Figure 33. Layout Diagram



APPLICATION INFORMATION

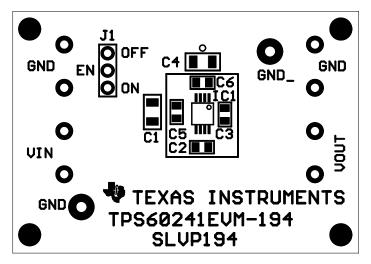


Figure 34. Top Silkscreen

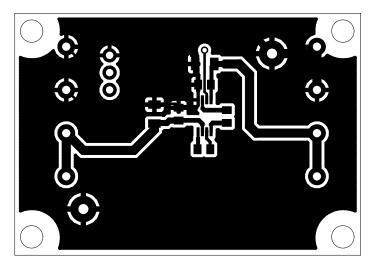


Figure 35. Top Layer

device family products

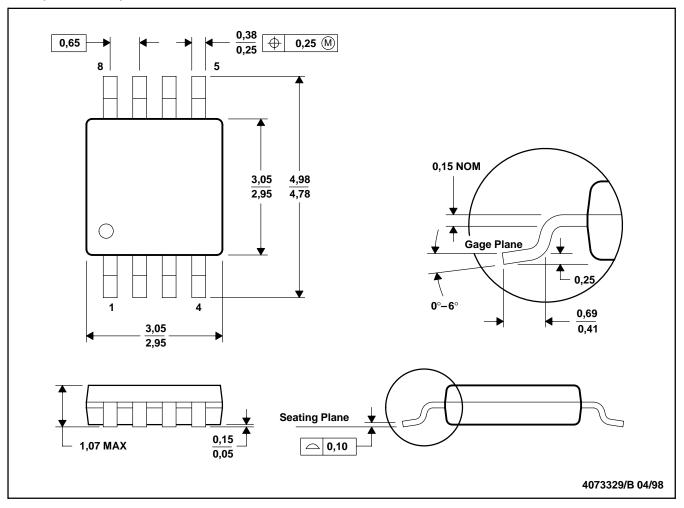
PART NUMBER	DESCRIPTION
REG710	30-mA switched cap dc/dc converter
REG711	50-mA switched cap dc/dc converter
TPS60110	Regulated 5-V, 300-mA low-noise charge pump dc/dc converter
TPS60111	Regulated 5-V, 150-mA low-noise charge pump dc/dc converter



MECHANICAL DATA

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-187





PACKAGE OPTION ADDENDUM

www.ti.com 28-May-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS60240DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60240DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60242DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGK	OBSOLETE	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60243DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

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compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

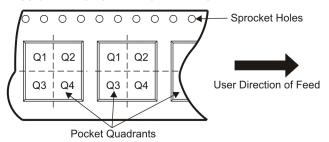


TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

- Reel Width (W1)

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1





*All dimensions are nominal

	1	1					
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60240DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60241DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60241DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60242DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60242DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60243DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60243DGKT	MSOP	DGK	8	250	190.5	212.7	31.8

24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
TPS60240DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI		.,	
TPS60240DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60241DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Sample
TPS60241DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Sample
TPS60241DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Sample
TPS60242DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60242DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYF	Sample
TPS60242DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYF	Sample
TPS60243DGK	OBSOLETE	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60243DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Sample
TPS60243DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Sample
TPS60243DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Sample
TPS60243DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Sample

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



PACKAGE OPTION ADDENDUM

24-Jan-2013

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

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*All dimensions are nominal

	T						
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60240DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60241DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60241DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60242DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60243DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60243DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0

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